



EMAP 2018

**2018 20th International Conference on
Electronic Materials and Packaging**

17 - 20 December 2018

Hong Kong University of Science and Technology



Call for Papers

The 2018 20th International Conference on Electronic Materials and Packaging (EMAP 2018) is a unique event for the electronic packaging community. This conference aims to bring together experts from industry, academia, and research to exchange their state-of-the-art technologies, recent developments, and visions for the future. EMAP 2018 will be held in Hong Kong from December 17th to December 20th 2018. The program includes invited and keynote presentations from world-renowned speakers, interactive sharing sessions, and technical short courses.

This year's conference will put a special emphasis on speaker-audience interaction. This special format will feature brief presentations followed by poster sessions. Each submitted paper will be accompanied by a poster which the speakers will present in a joint session. Thus, EMAP 2018 offers not only a unique opportunity for the audience to take a deeper dive into the presented content through direct conversation with the speakers but also valuable networking opportunities for all parties involved.

The EMAP 2018 Committee is now inviting you to submit your original work to this conference and join EMAP 2018. The conference covers all aspect of these interdisciplinary technologies including, but not limited to:

Topics:

- Additive Manufacturing
- Advanced Packaging Technologies
- Emerging Technologies
- Design, Modeling and Simulation
- High Density and 3D Packaging
- Interconnections
- Materials and Processing
- Microsystems Packaging and Applications
- Optoelectronics and Photonics
- Power Electronics Integration
- Quality and Reliability Assessment
- System Integration
- Thermal Management

Please download the abstract template from our website (<http://emap2018.ust.hk>) and submit to emap2018@ust.hk on or before August 31st 2018. Register before November 15th 2018 to enjoy the early bird rate! We are looking forward to seeing you at EMAP 2018.

Abstract Due: 31st August 2018